

ELECTRICS & ELECTRONICS | SEMICOSIL® 961 TC

THERMALLY CONDUCTIVE GAP FILLER WITH 2.3 W/mK

SEMICOSIL® 961 TC

WACKER expands its thermal conductive material portfolio by a new gap filler for electronics and electrical applications as well as for battery applications. The constantly increasing demand for heat dissipation between two substrates with high tolerances calls for a gap filler, which is easy and cost effectively to handle and renders save functionality and durability.

Product Description

Two component addition curing silicone, which cures at room temperature or faster at elevated temperature to a soft and tacky gap filling material with a thermal conductivity of 2.3 W/mK.

Features of SEMICOSIL® 961 TC

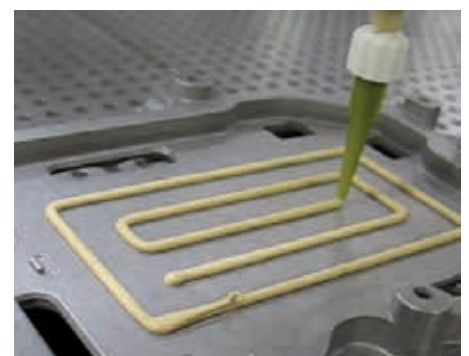
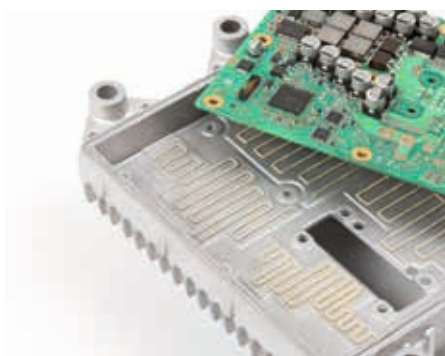
- High dispensing speed for short cycle time
- Low volatile content
- UL 94 V-0 rating (tested at WACKER)
- Constant properties between -50 °C and +180 °C
- Low abrasiveness

Applications

- Automotive electronics
- Battery assembly for Electric Vehicles (EV) and Hybrid Electric Vehicles (HEV)
- Power electronics
- Consumer electronics

Product Information				
Property	Test Method	Unit	Value	
Part			A	B
Product Data Uncured				
Color			White	Yellow
Viscosity at 23 °C, cone-plate-viscosimeter	ISO 3219, D = 10 1/s	[mPa s]	130,000	130,000
Density at 23 °C		[g/cm ³]	2.9	2.9
Product Data Catalyzed A+B				
Mixing ratio (parts by weight)		A : B	1 : 1	
Viscosity catalyzed, at 23 °C	ISO 3219, D = 10 1/s	[mPa s]	130,000	
Pot life (up to 300,000 mPa s), at 23 °C		[min]	60	
Product Data Cured				
Color			Yellow	
Density at 23 °C, in water	DIN 53 479 A / ISO 2781	[g/cm ³]	2.9	
Hardness Shore A	DIN 53 505 / ISO 868		25	
Hardness Shore 00	DIN 53 505 / ISO 868		55	
Thermal conductivity	ASTM D5470-12	[W/mK]	2.3	
Content siloxane D4-D8	NSCG012	[ppm]	< 350	
Heat capacity at 30 °C		[J/gK]	1.0	
Flame rating, vertical test	Internal test acc. UL94		V-0	
Maximum particle size		[micron]	90	
Volume resistivity	IEC 93	[Ohm.cm]	>10 ¹³	
Dielectric strength	IEC 93	[kV/mm]	8	
Cured for 10 min at 165 °C				

These figures are only intended as a guide and should not be used in preparing specifications.



**Processing Time**

Shelf life	6 months
Potlife at 23 °C	60 min

Curing Time

25 °C	300 min
100 °C	5 min

Packaging Options

Pail, Hobbock	30 kg / 10.7 l
EURO cartridge	900 gr / 300 cc
SEMCO® on request*	20 Oz, 6 Oz

* For sampling

